

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 7,056,766 B2  
APPLICATION NO. : 10/731831  
DATED : June 6, 2006  
INVENTOR(S) : Hei Ming Shiu

Page 1 of 1


It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In Column 7, Line 11, Claim No. 14:  
Change "dice, comprising" to --die, comprising--  
In Column 7, Line 18, Claim No. 14:  
Change "dice to the mold" to --die to the mold--  
In Column 7, Line 19, Claim No. 14:  
Change "of the dice have" to --of the die have--  
In Column 7, Line 22, Claim No. 14:  
Change "of the dice to" to --of the die to--  
In Column 7, Line 24, Claim No. 14:  
Change "dice;" to --die;--  
In Column 7, Line 25, Claim No. 14:  
Change "encapsulating the dice," to --encapsulating the die,--  
In Column 7, Line 28, Claim No. 14:  
Change "such that a bottom" to --such that bottom--  
In Column 7, Line 30, Claim No. 14:  
Change "encapsulated dice to" to --encapsulated die to--  
In Column 8, Line 14, Claim No. 20:  
Change "wherein the dice" to --wherein the die--  
In Column 8, Line 15, Claim No. 20:  
Change "side of the dice" to --side of the die--

This certificate supersedes the Certificate of Correction issued May 20, 2008.

Signed and Sealed this

Seventeenth Day of June, 2008



JON W. DUDAS  
*Director of the United States Patent and Trademark Office*